

Hongxia Lu

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EDUCATION

University of Berkeley, HAAS School of Business

Berkeley, CA

MBA Candidate

May 2018

- GMAT Quantitative 50

Cornell University

Ithaca, NY

Ph.D. Materials Science and Engineering

May 2006

- GPA 3.94/4.0, GRE Quantitative 800
- Hsien Wu and Daisy Yen Wu Scholarship (2004, 10 out of 3200 students)
- Vice President for public relationship, International Student Programming Board (2005)

Shanghai Institute of Ceramics, Chinese Academy of Sciences (*Top 2 in Ceramics in China*)

Shanghai, China

Master of Engineer, Materials Science and Engineering

07/2000

- GPA 3.91/4.0
- President, Graduate Student Association

Shandong Light Industry Institute

Jinan, China

Bachelor of Engineer, Materials Science and Engineering (MSE)

07/1997

- GPA 3.87/4.0, First Class with Honors, Ranked Top 1% in MSE Department

WORK AND LEADERSHIP EXPERIENCE

Intel Corp.

Chandler, AZ

Program Manager

2010-present

Planned and managed multiple programs for product definition and development; led as primary consensus builder/decision maker for cross-organizational product teams

- **Led the 1st lead free conversion program using external silicon for RoHS compliance:** generated cost savings of \$1.2M by certifying new materials/processes.
- **Managed products transition from Intel acquisition:** generated revenue of 2M+ by certifying products with implementing Intel business process. Led the team of 14 for smooth products transition.
- **Delivered the 1st Intel ultra-thin substrate technology** to enable Intel mobile roadmap change for Thin-n-Light. Defined product requirements with customers through ambiguity.

Program Integrator

2007-2010

Led 10+ person cross-functional team (marketing, finance, design, quality, etc.); managed integration of CPU component project; supported 4 ODM customers in the design tuning-ins and bought-offs

- **Solved key issue in Intel SandyBridge component development:** generated \$5+ million cost savings by implementing innovative design change to turn-around product certification crisis.
- **Achieved design breakthroughs for product differentiation:** reduced 30% cost (\$1M) in providing solutions of using a common manufacturing infrastructure for 6 electrically incompatible products
- Authored 3 internal papers for advanced electronic packaging technologies.

Module Engineer

2006-2007

Aligned both Intel and assembly subcontractor roadmap; accomplished multiple package development with team

- **Substantially improved module yield** to 99% from 63% through leading module task forces with assembly subcontractors to ensure flash memory product launch on time.

Co-Founder and Vice President, Intel Chinese Employee Network

09/11-Present

Co-led a team of 14 to promote diversity by organizing 11 events of speeches, diversity fairs, and holiday celebration in a year. Drove membership to 200+ since club was founded

- Nominated Intel Outstanding Employee Group (four out of 32 Intel Arizona employee groups) in 2013 in recognition of outstanding team efforts in diversity

OTHER

- Other Language: Mandarin (Native)
- Skills: Project Management Professional (PMI), AZ state realtor, licensed tour guide in China
- Interest: Ballroom dance, travel, reading, movie, volunteering
- Publications and presentations: (Co-)authored 8 papers, 3 conference presentations